The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Original) A heat curable adhesive composition comprising: a caprolactone-modified epoxy resin; and a tack reducing component that is a melamine/isocyanuric acid adduct or an organic compound that can be dissolved or dispersed with the modified epoxy resin in a solvent and has a glass transition temperature of 110° C or higher and is not decomposed or modified by heating at a temperature of 250° C or higher within a minute.

2. (Original) A process for preparing the heat curable adhesive composition of claim 1 comprising: providing a caprolactone-modified epoxy resin; and blending therewith the tack reducing component.

3. (Original) An adhesive article comprising:

a layer of the heat curable adhesive composition according to claim 1; and

a backing layer carrying said adhesive layer on at least a portion of the backing layer.

4. (Original) A semiconductor apparatus comprising a substrate having at least one semiconductor component mounted thereon, wherein said semiconductor component is fixed to a component-mounting surface of said substrate via a layer of the heat curable adhesive composition according to claim 1.

5. (Currently Amended) The semiconductor apparatus according to [[Claim]]claim 4 further comprising another semiconductor component mounted to the at least one semiconductor component.

6. (Original) An adhesive article comprising a heat curable adhesive layer containing a caprolactone-modified epoxy resin, and a stretchable backing layer, optionally having an elongation of not less than 10%.

7. (Original) A semiconductor apparatus comprising a substrate having at least one semiconductor component mounted thereon, wherein the semiconductor component is fixed on the surface of the substrate by means of a heat curable adhesive layer containing a caprolactone-modified epoxy resin.

8. (Original) A process for preparing a semiconductor apparatus comprising a substrate having at least one semiconductor component mounted thereon comprising:

laminating an adhesive article on one side of a semiconductor wafer having a plurality of the semiconductor components fabricated therein, the adhesive article comprising a heat curable adhesive layer containing a caprolactone-modified epoxy resin and a stretchable backing layer, optionally wherein said backing layer has an elongation of not less than 10%;

discretely separating the semiconductor components while maintaining the semiconductor wafer and adhesive article in a laminated state;

stretching the backing layer of the adhesive article, followed by separating the semiconductor components with the heat curable adhesive layer adhered thereto from the backing layer; and

fixing the semiconductor components to the surface of the substrate by means of the heat curable adhesive layer.